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Webinar Course Description

Introduction to Microelectronics Packaging (3 sessions)

This three part webinar series is intended for individuals unfamiliar with microelectronics packaging technology. The first session broadly describes packaging terminology and reviews the myriad of acronyms used throughout the electronics industry. The instructor then breaks down the technology in terms of industry segments, beginning with low volume complex hermetic packages for the military use, and then the latest developments in commercial microelectronics packaging for cell phones and handheld wireless devices. Lots of pictures along with simple explanations will help a new manager or engineer understand the technology drivers and key aspects of microelectronic packaging technology.

Webinar Outline

Introduction to Microelectronic Packaging

Terminology and Product Definitions
- Hybrids, MCMs, Microwave Modules, MEMS, Optoelectronic Devices
- SMT (Surface Mount Technology) leaded and leadless packages, BGAs, CSPs

Market Segments and Technology Drivers

Typical Low Volume Complex Hermetic Military Process Flow
- Hermetic packaging processes

High Speed Automated Commercial Processes
- Plastic encapsulation and molding processes

IC Wafer Fabrication Technology Overview

Substrate/Board Manufacturing Technologies
- Thick and thin film ceramic LTCC
- Printed Circuit Boards (PCB)

Fundamentals of Component Attach

Interconnect Technology: Wirebonding, Flip Chips and 3D Chip Stacking

Emerging Trends

Summary and Course Review